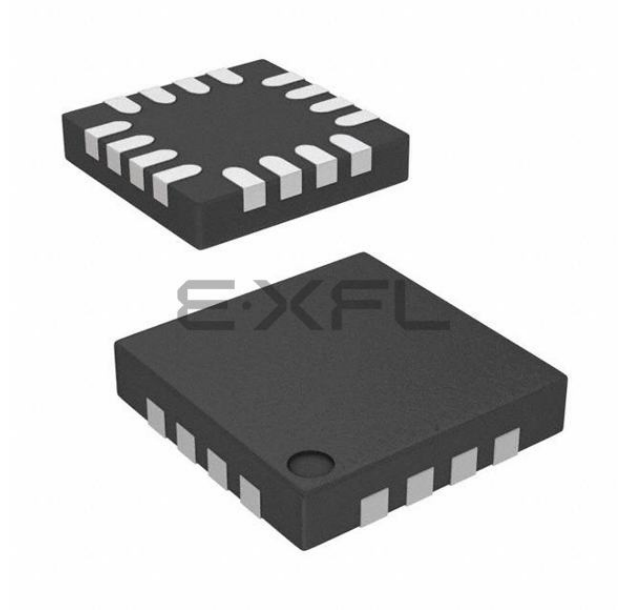

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	M8C
Core Size	8-Bit
Speed	12MHz
Connectivity	I²C, SPI
Peripherals	LVD, POR, WDT
Number of I/O	13
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 5.25V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	16-UFQFN
Supplier Device Package	16-QFN (3x3)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c20234-12lkxi

PSoC Functional Overview

The PSoC family consists of many *Programmable System-on-Chips with On-Chip Controller* devices. These devices are designed to replace multiple traditional MCU based system components with one low cost single chip programmable component. A PSoC device includes configurable analog and digital blocks and programmable interconnect. This architecture enables the user to create customized peripheral configurations to match the requirements of each individual application. Additionally, a fast CPU, flash program memory, SRAM data memory, and configurable I/O are included in a range of convenient pinouts.

The PSoC architecture for this device family, as shown in Figure 2, consists of three main areas: the Core, the System Resources, and the CapSense Analog System. A common versatile bus enables connection between I/O and the analog system. Each CY8C20x34 PSoC device includes a dedicated CapSense block that provides sensing and scanning control circuitry for capacitive sensing applications. Depending on the PSoC package, up to 28 general purpose I/O (GPIO) are also included. The GPIO provide access to the MCU and analog mux.

PSoC Core

The PSoC Core is a powerful engine that supports a rich instruction set. It encompasses SRAM for data storage, an interrupt controller, sleep and watchdog timers, IMO, and ILO. The CPU core, called the M8C, is a powerful processor with speeds up to 12 MHz. The M8C is a two MIPS, 8-bit Harvard-architecture microprocessor.

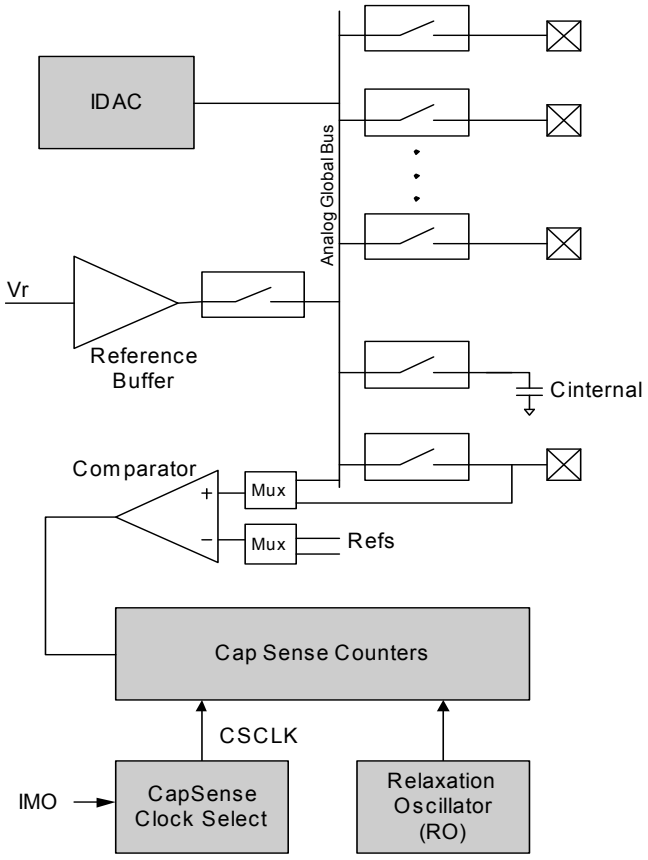
System Resources provide additional capability such as a configurable I^2C slave or SPI master-slave communication interface and various system resets supported by the M8C.

The Analog System consists of the CapSense PSoC block and an internal 1.8 V analog reference. Together they support capacitive sensing of up to 28 inputs.

CapSense Analog System

The Analog System contains the capacitive sensing hardware. Several hardware algorithms are supported. This hardware performs capacitive sensing and scanning without requiring external components. Capacitive sensing is configurable on each GPIO pin. Scanning of enabled CapSense pins is completed quickly and easily across multiple ports.

Figure 2. Analog System Block Diagram



Analog Multiplexer System

The Analog Mux Bus connects to every GPIO pin. Pins are connected to the bus individually or in any combination. The bus also connects to the analog system for analysis with the CapSense block comparator.

Switch control logic enables selected pins to precharge continuously under hardware control. This enables capacitive measurement for applications such as touch sensing. Other multiplexer applications include:

- Complex capacitive sensing interfaces such as sliders and touch pads
- Chip-wide mux that enables analog input from any I/O pin
- Crosspoint connection between any I/O pin combinations

Getting Started

For in-depth information, along with detailed programming details, see the *PSoC® Technical Reference Manual*.

For up-to-date ordering, packaging, and electrical specification information, see the latest PSoC device datasheets on the web.

Application Notes

Cypress application notes are an excellent introduction to the wide variety of possible PSoC designs.

Development Kits

PSoC Development Kits are available online from and through a growing number of regional and global distributors, which include Arrow, Avnet, Digi-Key, Farnell, Future Electronics, and Newark.

Training

Free PSoC technical training (on demand, webinars, and workshops), which is available online via www.cypress.com, covers a wide variety of topics and skill levels to assist you in your designs.

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16-Pin SOIC Pinout

Figure 4. CY8C20234-12SXI 16-Pin SOIC Pinout

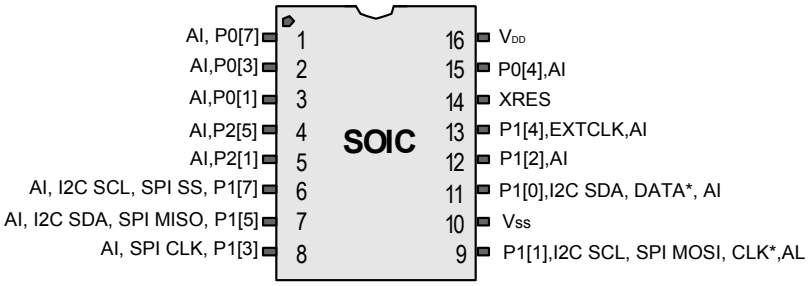


Table 3. Pin Definitions – CY8C20234 16-Pin (SOIC)

Pin No.	Digital	Analog	Name	Description
1	I/O	I	P0[7]	Analog column mux input
2	I/O	I	P0[3]	Analog column mux input and column input, integrating input
3	I/O	I	P0[1]	Analog column mux input, integrating input
4	I/O	I	P2[5]	Analog column mux input
5	I/O	I	P2[1]	Analog column mux input
6	I/O	I	P1[7]	I2C serial clock (SCL), SPI SS
7	I/O	I	P1[5]	I2C serial data (SDA),SPI MISO
8	I/O	I	P1[3]	Analog column mux input, SPI CLK
9	I/O	I	P1[1]	I2C serial clock (SCL), ISSP-SCLK,SPI MOSI
10	Power		V_{SS}	Ground connection
11	I/O	I	P1[0]	I2C serial data (SDA), ISSP-SDATA
12	I/O	I	P1[2]	Analog column mux input
13	I/O	I	P1[4]	Analog column mux input, optional external clock input (EXTCLK)
14	I/O	I	XRES	XRES
15	I/O	I	P0[4]	Analog column mux input
16	Power		V_{DD}	Supply voltage

A = Analog, I = Input, O = Output, OH = 5 mA High Output Drive.

Table 13. 5-V and 3.3-V DC GPIO Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
V_{OH7}	High output voltage Port 1 pins with 2.4 V LDO regulator enabled	2.1	2.4	2.7	V	I_{OH} < 10 µA, $V_{DD} \geq$ 3.0 V , maximum of 20 mA source current in all I/Os.
V_{OH8}	High output voltage Port 1 pins with 2.4 V LDO regulator enabled	2.0	–	–	V	I_{OH} < 200 µA, $V_{DD} \geq$ 3.0 V, maximum of 20 mA source current in all I/Os.
V_{OH9}	High output voltage Port 1 pins with 1.8 V LDO regulator enabled	1.6	1.8	2.0	V	I_{OH} < 10 µA 3.0V ≤ V_{DD} ≤ 3.6 V 0 °C ≤ T_A ≤ 85 °C Maximum of 20 mA source current in all I/Os.
V_{OH10}	High output voltage Port 1 pins with 1.8 V LDO regulator enabled	1.5	–	–	V	I_{OH} < 100 µA. 3.0V ≤ V_{DD} ≤ 3.6 V. 0 °C ≤ T_A ≤ 85 °C. Maximum of 20 mA source current in all I/Os.
V_{OL}	Low output voltage	–	–	0.75	V	I_{OL} = 20 mA, V_{DD} > 3.0 V, maximum of 60 mA sink current on even port pins (for example, P0[2] and P1[4]) and 60 mA sink current on odd port pins (for example, P0[3] and P1[5]).
I_{OH}	High level source current	–	–	20	mA	V_{OH} = V_{DD} – 0.9. See the limitations of the total current in the Notes for V_{OH}.
I_{OH2}	High level source current port 0, 2, or 3 pins	1	–	–	mA	V_{OH} = V_{DD} – 0.9, for the limitations of the total current and I_{OH} at other V_{OH} levels, see the Notes for V_{OH}.
I_{OH4}	High level source current port 1 Pins with LDO regulator disabled	5	–	–	mA	V_{OH} = V_{DD} – 0.9, for the limitations of the total current and I_{OH} at other V_{OH} levels, see the Notes for V_{OH}.
I_{OL}	Low level sink current	20	–	–	mA	V_{OL} = 0.75 V, see the limitations of the total current in the Notes for V_{OL}
V_{IL}	Input low voltage	–	–	0.8	V	3.6 V ≤ V_{DD} ≤ 5.25 V
V_{IH}	Input high voltage	2.0	–	–	V	3.6 V ≤ V_{DD} ≤ 5.25 V
V_H	Input hysteresis voltage	–	140	–	mV	
I_{IL}	Input leakage (absolute value)	–	1	–	nA	Gross tested to 1 µA
C_{IN}	Capacitive load on pins as input	0.5	1.7	5	pF	Package and pin dependent Temperature = 25 °C
C_{OUT}	Capacitive load on pins as output	0.5	1.7	5	pF	Package and pin dependent Temperature = 25 °C

Table 14. 2.7-V DC GPIO Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
R_{PU}	Pull-up resistor	4	5.6	8	kΩ	
V_{OH1}	High output voltage Port 1 pins with LDO regulator disabled	V_{DD} – 0.2	–	–	V	I_{OH} < 10 µA, maximum of 10 mA source current in all I/Os.
V_{OH2}	High output voltage Port 1 pins with LDO regulator disabled	V_{DD} – 0.5	–	–	V	I_{OH} = 2 mA, maximum of 10 mA source current in all I/Os.
V_{OL}	Low output voltage	–	–	0.75	V	I_{OL} = 10 mA, maximum of 30 mA sink current on even port pins (for example, P0[2] and P1[4]) and 30 mA sink current on odd port pins (for example, P0[3] and P1[5]).
I_{OH2}	High level source current port 1 Pins with LDO regulator disabled	2	–	–	mA	V_{OH} = V_{DD} – 0.5, for the limitations of the total current and I_{OH} at other V_{OH} levels see the notes for V_{OH}.
I_{OL}	Low level sink current	10	–	–	mA	V_{OH} = .75 V, see the limitations of the total current in the note for V_{OL}
V_{OLP1}	Low output voltage port 1 pins	–	–	0.4	V	I_{OL} = 5 mA Maximum of 50 mA sink current on even port pins (for example, P0[2] and P3[4]) and 50 mA sink current on odd port pins (for example, P0[3] and P2[5]). 2.4 V ≤ V_{DD} < 3.6 V
V_{IL}	Input low voltage	–	–	0.75	V	2.4 V ≤ V_{DD} < 3.6 V
V_{IH1}	Input high voltage	1.4	–	–	V	2.4 V ≤ V_{DD} < 2.7 V
V_{IH2}	Input high voltage	1.6	–	–	V	2.7 V ≤ V_{DD} < 3.6 V
V_H	Input hysteresis voltage	–	60	–	mV	
I_{IL}	Input leakage (absolute value)	–	1	–	nA	Gross tested to 1 µA
C_{IN}	Capacitive load on pins as input	0.5	1.7	5	pF	Package and pin dependent Temperature = 25 °C
C_{OUT}	Capacitive load on pins as output	0.5	1.7	5	pF	Package and pin dependent Temperature = 25 °C

DC Analog Mux Bus Specifications

Table 15 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, or 2.4 V to 3.0 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters apply to 5 V, 3.3 V, or 2.7 V at 25 °C. These are for design guidance only.

Table 15. DC Analog Mux Bus Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
R_{SW}	Switch resistance to common analog bus	–	–	400 800	Ω Ω	V_{DD} ≥ 2.7 V 2.4 V ≤ V_{DD} ≤ 2.7 V

Table 20. 2.7-V AC Chip Level Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
F_{CPU1}	CPU Frequency (2.7 V nominal)	0.75	–	3.25	MHz	SLIMO mode = 0
F_{32K1}	Internal low speed oscillator frequency	8	32	96	kHz	
F_{32K_U}	Internal low speed oscillator (ILO) untrimmed frequency	5	–	100	kHz	After a reset and before the M8C starts to run, the ILO is not trimmed. See the System Resets section of the PSoC Technical Reference Manual for details on this timing.
F_{IMO12}	IMO stability for 12 MHz (commercial temperature)[25]	11.0	12	12.9	MHz	Trimmed for 2.7 V operation using factory trim values. See Figure 11 on page 19, SLIMO mode = 0.
F_{IMO6}	IMO stability for 6 MHz (commercial temperature)	5.5	6.0	6.5	MHz	Trimmed for 2.7 V operation using factory trim values. See Figure 11 on page 19, SLIMO mode = 1.
DC_{IMO}	Duty cycle of IMO	40	50	60	%	
DC_{ILO}	Internal low speed oscillator duty cycle	20	50	80	%	
t_{XRST}	External reset pulse width	10	–	–	µs	
$t_{POWERUP}$	Time from end of POR to CPU executing code	–	16	100	ms	Power-up from 0 V. See the System Resets section of the PSoC Technical Reference Manual
SR_{POWER_UP}	Power supply slew rate	–	–	250	V/ms	
t_{JIT_IMO} [26]	12 MHz IMO cycle-to-cycle jitter (RMS)	–	500	900	ps	
	12 MHz IMO long term N cycle-to-cycle jitter (RMS)	–	800	1400	ps	N = 32
	12 MHz IMO period jitter (RMS)	–	300	500	ps	

Notes
25. 0 °C to 70 °C ambient, V_{DD} = 3.3 V.
26. Refer to Cypress Jitter Specifications Application Note – AN5054 at http://www.cypress.com for more information.

AC GPIO Specifications

Table 21 and Table 22 list the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, or 2.4 V to 3.0 V and –40 °C ≤ T_A ≤ 85 °C respectively. Typical parameters apply to 5 V, 3.3 V, or 2.7 V at 25 °C. These are for design guidance only.

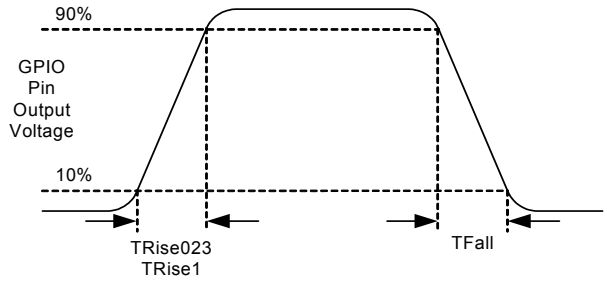
Table 21. 5-V and 3.3-V AC GPIO Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
F_{GPIO}	GPIO operating frequency	0	–	6	MHz	Normal strong mode, port 1.
$t_{RISE023}$	Rise time, strong mode, Cload = 50 pF ports 0, 2, 3	15	–	80	ns	V_{DD} = 3.0 to 3.6 V and 4.75 V to 5.25 V, 10% to 90%
t_{RISE1}	Rise time, strong mode, Cload = 50 pF port 1	10	–	50	ns	V_{DD} = 3.0 V to 3.6 V, 10% to 90%
t_{FALL}	Fall time, strong mode, Cload = 50 pF all ports	10	–	50	ns	V_{DD} = 3.0 V to 3.6 V and 4.75 V to 5.25 V, 10% to 90%

Table 22. 2.7-V AC GPIO Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
F_{GPIO}	GPIO operating frequency	0	–	1.5	MHz	Normal strong mode, port 1.
$t_{RISE023}$	Rise time, strong mode, Cload = 50 pF ports 0, 2, 3	15	–	100	ns	V_{DD} = 2.4 V to 3.0 V, 10% to 90%
t_{RISE1}	Rise time, strong mode, Cload = 50 pF port 1	10	–	70	ns	V_{DD} = 2.4 V to 3.0 V, 10% to 90%
t_{FALL}	Fall time, strong mode, Cload = 50 pF all Ports	10	–	70	ns	V_{DD} = 2.4 V to 3.0 V, 10% to 90%

Figure 12. GPIO Timing Diagram



AC Comparator Specifications

Table 23 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, or 2.4 V to 3.0 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters apply to 5 V, 3.3 V, or 2.7 V at 25 °C. These are for design guidance only.

Table 23. AC Comparator Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
t_{COMP}	Comparator response time, 50 mV overdrive	–	–	100 200	ns ns	V_{DD} ≥ 3.0 V. 2.4 V < V_{CC} < 3.0 V.

AC External Clock Specifications

Table 24, Table 25, Table 26, and Table 27 list the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, or 2.4 V to 3.0 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters apply to 5 V, 3.3 V, or 2.7 V at 25 °C. These are for design guidance only.

Table 24. 5-V AC External Clock Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
F_{OSCEXT}	Frequency	0.750	–	12.6	MHz	
–	High period	38	–	5300	ns	
–	Low period	38	–	–	ns	
–	Power-up IMO to switch	150	–	–	µs	

Table 25. 3.3-V AC External Clock Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
F_{OSCEXT}	Frequency with CPU clock divide by 1	0.750	–	12.6	MHz	Maximum CPU frequency is 12 MHz at 3.3 V. With the CPU clock divider set to 1, the external clock must adhere to the maximum frequency and duty cycle requirements.
–	High period with CPU clock divide by 1	41.7	–	5300	ns	
–	Low period with CPU clock divide by 1	41.7	–	–	ns	
–	Power-up IMO to switch	150	–	–	µs	

Table 26. 2.7-V (Nominal) AC External Clock Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
F_{OSCEXT}	Frequency with CPU clock divide by 1	0.750	–	3.08	MHz	Maximum CPU frequency is 3 MHz at 2.7 V. With the CPU clock divider set to 1, the external clock must adhere to the maximum frequency and duty cycle requirements.
F_{OSCEXT}	Frequency with CPU clock divide by 2 or greater	0.15	–	6.35	MHz	If the frequency of the external clock is greater than 3 MHz, the CPU clock divider is set to 2 or greater. In this case, the CPU clock divider ensures that the fifty percent duty cycle requirement is met.
–	High period with CPU clock divide by 1	160	–	5300	ns	
–	Low period with CPU clock divide by 1	160	–	–	ns	
–	Power-up IMO to switch	150	–	–	µs	

Table 27. 2.7-V (Minimum) AC External Clock Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
F_{OSCEXT}	Frequency with CPU clock divide by 1	0.750	–	6.3	MHz	Maximum CPU frequency is 6 MHz at 2.7 V. With the CPU clock divider set to 1, the external clock must adhere to the maximum frequency and duty cycle requirements.
F_{OSCEXT}	Frequency with CPU clock divide by 2 or greater	0.15	–	12.6	MHz	If the frequency of the external clock is greater than 6 MHz, the CPU clock divider is set to 2 or greater. In this case, the CPU clock divider ensures that the fifty percent duty cycle requirement is met.
–	High period with CPU clock divide by 1	160	–	5300	ns	
–	Low period with CPU clock divide by 1	160	–	–	ns	
–	Power-up IMO to switch	150	–	–	µs	

Packaging Dimensions

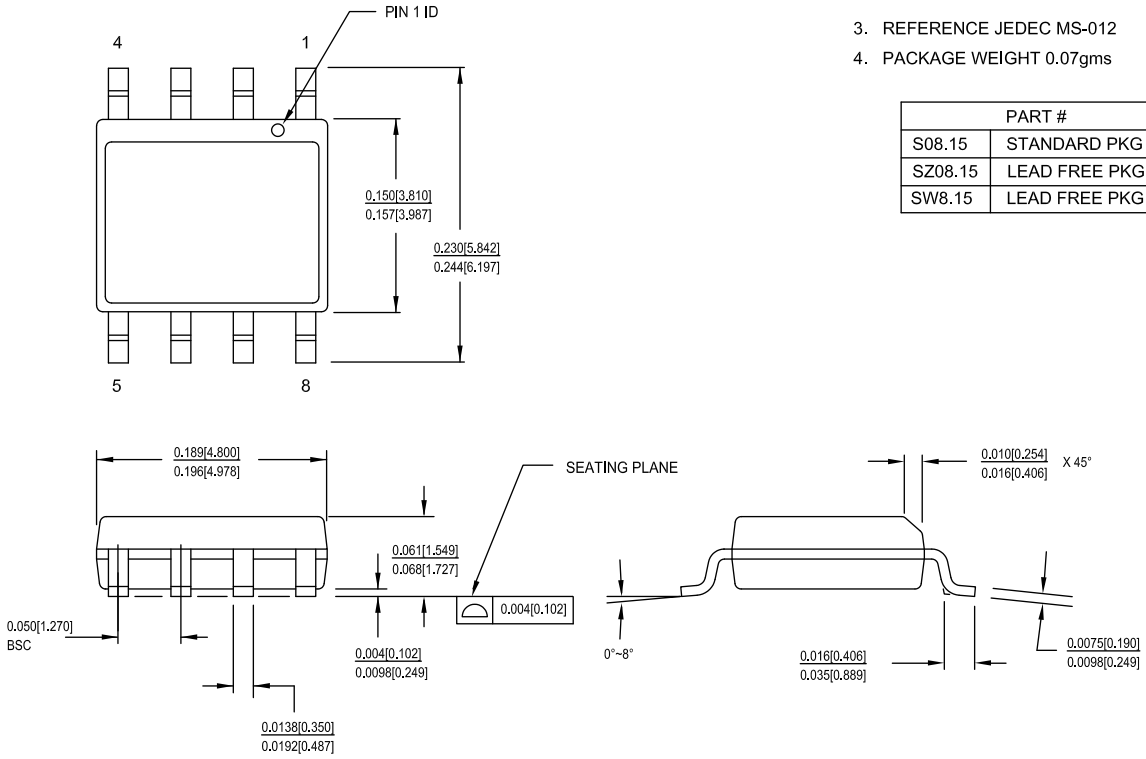
This section illustrates the packaging specifications for the CY8C20234, CY8C20334, CY8C20434, CY8C20534, and CY8C20634 PSoC devices along with the thermal impedances for each package.

Important Note Emulation tools may require a larger area on the target PCB than the chip's footprint. For a detailed description of the emulation tools' dimensions, refer to the emulator pod drawings at http://www.cypress.com.

Figure 14. 8-pin SOIC (150 Mils)

1. DIMENSIONS IN INCHES[MM] MIN.
   MAX.
2. PIN 1 ID IS OPTIONAL,
   ROUND ON SINGLE LEADFRAME
   RECTANGULAR ON MATRIX LEADFRAME
3. REFERENCE JEDEC MS-012
4. PACKAGE WEIGHT 0.07gms

PART #	
S08.15	STANDARD PKG
SZ08.15	LEAD FREE PKG
SW8.15	LEAD FREE PKG



51-85066 *G

Figure 15. 16-Pin SOIC (150 Mils)

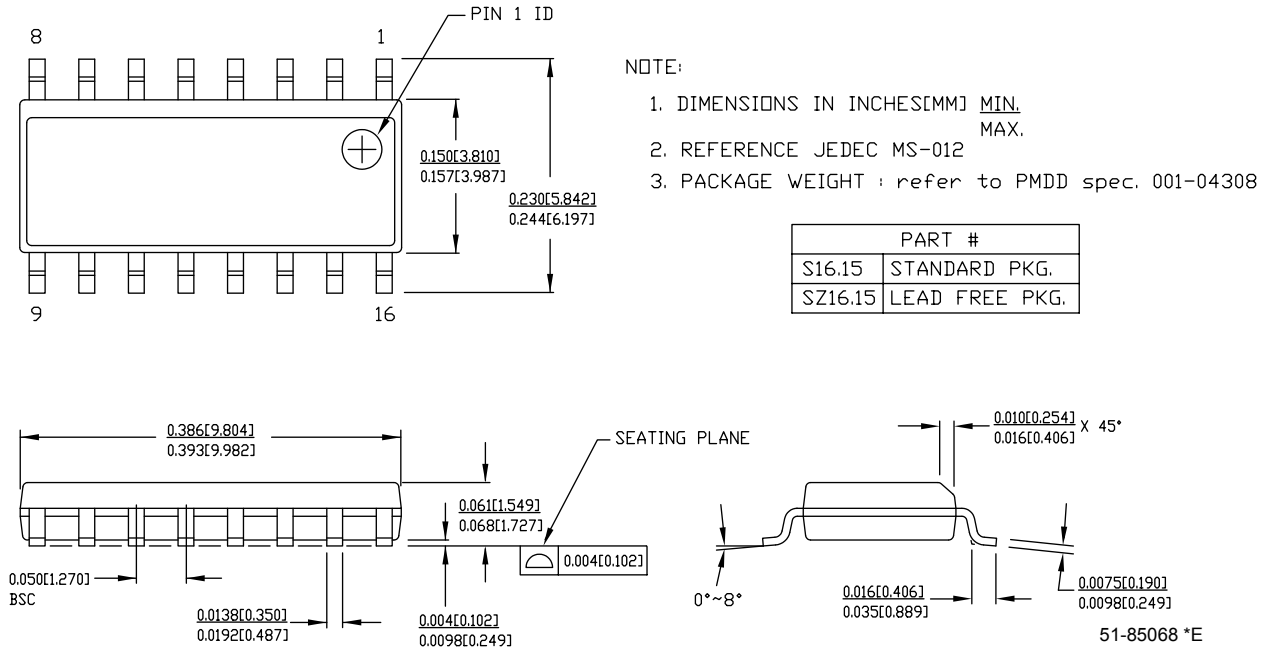


Figure 16. 48-Pin (7 × 7 × 1.0 mm) QFN

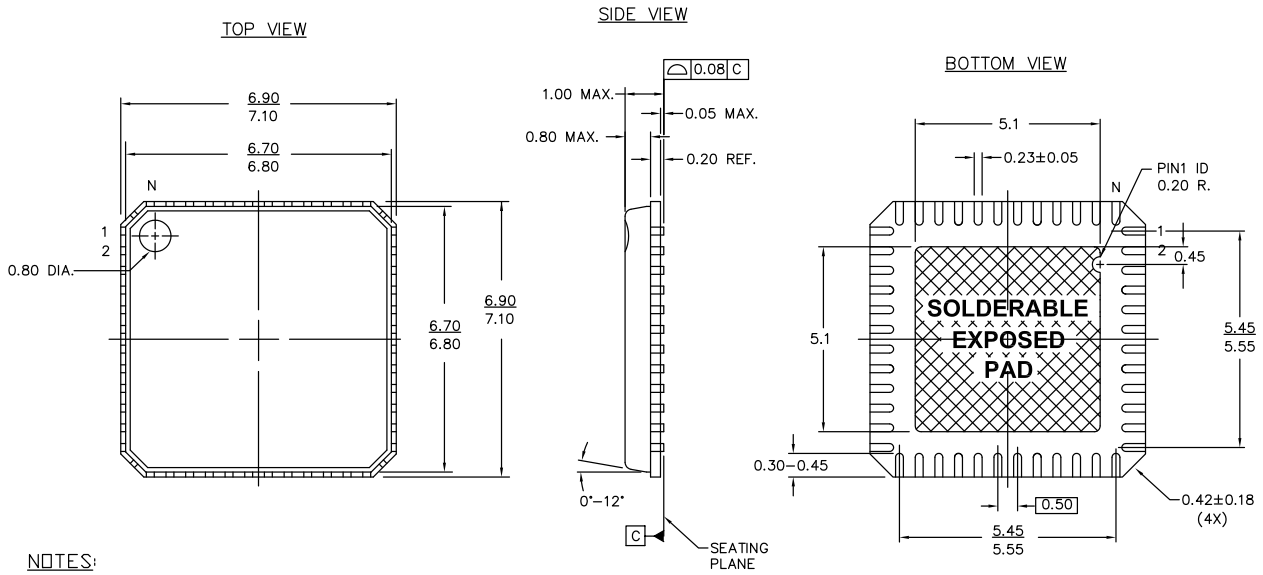
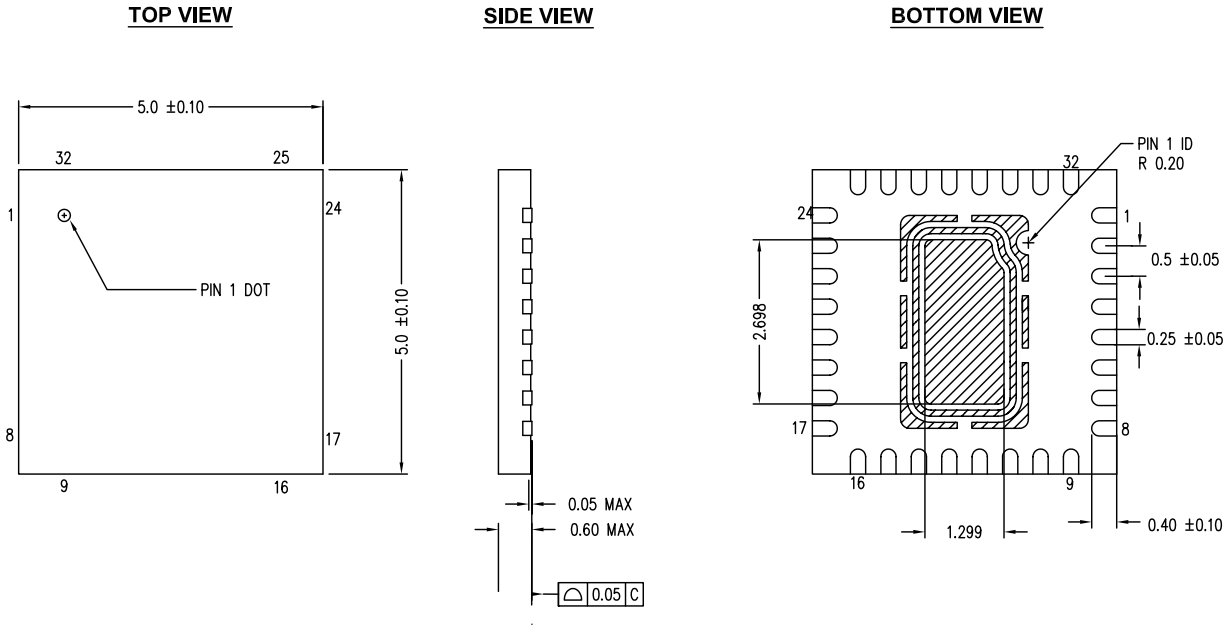


Figure 19. 32-Pin QFN 5 × 5 × 0.55 mm (Sawn)

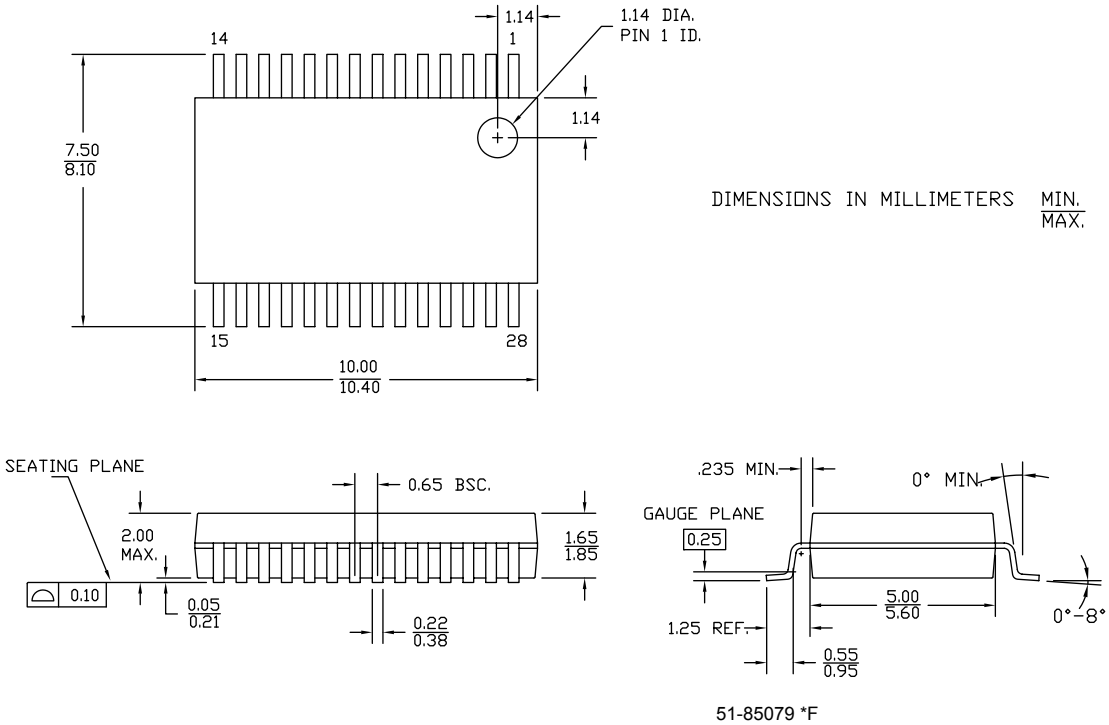


NOTES:

1. HATCH AREA IS SOLDERABLE EXPOSED PAD
2. BASED ON REF JEDEC # MO-248
3. PACKAGE WEIGHT: 38mg ± 4 mg
4. ALL DIMENSIONS ARE IN MILLIMETERS

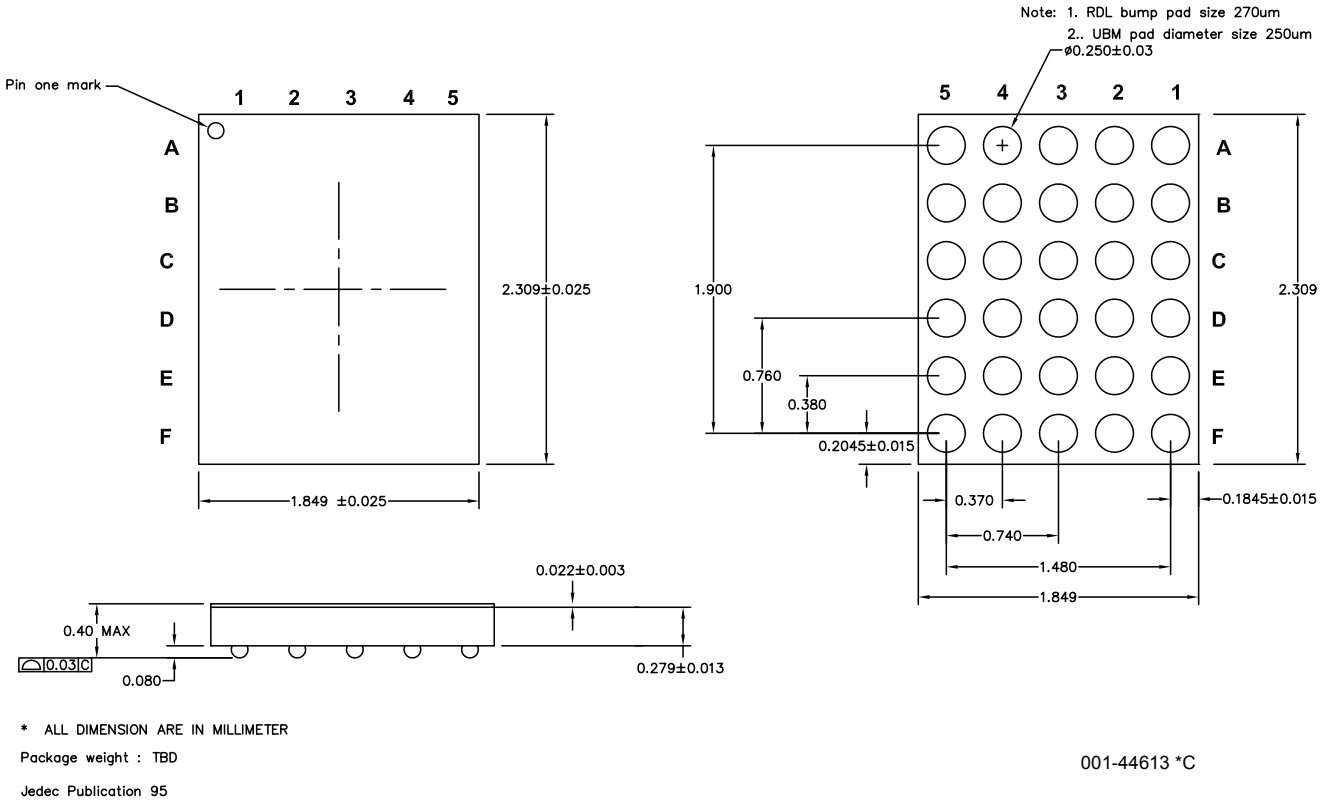
001-48913 *D

Figure 20. 28-pin SSOP (210 Mils)



51-85079 *F

Figure 21. 30-Ball (1.85 × 2.31 × 0.40 mm) WLCSP



Important Note For information on the preferred dimensions for mounting the QFN packages, see the application note *Design Guidelines for Cypress Quad Flat No Extended Lead (QFN) Packaged Devices – AN72845* available at http://www.cypress.com.

It is important to note that pinned vias for thermal conduction are not required for the low power 24, 32, and 48-pin QFN PSoC devices.

Thermal Impedances

Table 33 illustrates the minimum solder reflow peak temperature to achieve good solderability.

Table 33. Thermal Impedances Per Package

Package	Typical θ_{JA} [28]
8 SOIC	127 °C/W
16 SOIC	80 °C/W
16 QFN	46 °C/W
24 QFN[29]	25 °C/W
28 SSOP	96 °C/W
30 WLCSP	54 °C/W
32 QFN[29]	27 °C/W
48 QFN[29]	28 °C/W

Solder Reflow Specifications

Table 34 shows the solder reflow temperature limits that must not be exceeded.

Table 34. Solder Reflow Specifications

Package	Maximum Peak Temperature (T_C)	Maximum Time above T_C – 5 °C
8-Pin SOIC	260 °C	30 seconds
16-Pin SOIC	260 °C	30 seconds
16-Pin QFN	260 °C	30 seconds
24-Pin QFN	260 °C	30 seconds
28-Pin SSOP	260 °C	30 seconds
30-Pin WLCSP	260 °C	30 seconds
32-Pin QFN	260 °C	30 seconds
48-Pin QFN	260 °C	30 seconds

Notes
28. $T_J = T_A$ + Power × θ_{JA}.
29. To achieve the thermal impedance specified for the QFN package, refer to application note *Design Guidelines for Cypress Quad Flat No Extended Lead (QFN) Packaged Devices – AN72845* available at http://www.cypress.com.
30. Higher temperatures is required based on the solder melting point. Typical temperatures for solder are 220 ±5 °C with Sn-Pb or 245 ± 5 °C with Sn-Ag-Cu paste. Refer to the solder manufacturer specifications.

Development Tool Selection

Software

PSoC Designer™

At the core of the PSoC development software suite is PSoC Designer, used to generate PSoC firmware applications. PSoC Designer is available free of charge at http://www.cypress.com and includes a free C compiler.

PSoC Programmer

PSoC Programmer is flexible enough and is used on the bench in development and also suitable for factory programming. PSoC Programmer works either as a standalone programming application or operates directly from PSoC Designer. PSoC Programmer software is compatible with both PSoC ICE Cube In-Circuit Emulator and PSoC MiniProg. PSoC programmer is available free of charge at http://www.cypress.com.

Development Kits

All development kits are sold at the Cypress Online Store.

CY3215-DK Basic Development Kit

The CY3215-DK is for prototyping and development with PSoC Designer. This kit supports in-circuit emulation and the software interface enables users to run, halt, and single step the processor and view the content of specific memory locations. PSoC Designer supports the advance emulation features also. The kit includes:

- PSoC Designer Software CD
- ICE-Cube In-Circuit Emulator
- ICE Flex-Pod for CY8C29x66 Family
- Cat-5 Adapter
- Mini-Eval Programming Board
- 110 ~ 240V Power Supply, Euro-Plug Adapter
- iMAGEcraft C Compiler (Registration Required)
- ISSP Cable
- USB 2.0 Cable and Blue Cat-5 Cable
- 2 CY8C29466-24PXI 28-PDIP Chip Samples

Evaluation Tools

All evaluation tools are sold at the Cypress Online Store.

CY3210-MiniProg1

The CY3210-MiniProg1 kit enables the user to program PSoC devices via the MiniProg1 programming unit. The MiniProg is a small, compact prototyping programmer that connects to the PC via a provided USB 2.0 cable. The kit includes:

- MiniProg Programming Unit
- MiniEval Socket Programming and Evaluation Board
- 28-Pin CY8C29466-24PXI PDIP PSoC Device Sample
- 28-Pin CY8C27443-24PXI PDIP PSoC Device Sample
- PSoC Designer Software CD
- Getting Started Guide
- USB 2.0 Cable

CY3210-PSoCEval1

The CY3210-PSoCEval1 kit features an evaluation board and the MiniProg1 programming unit. The evaluation board includes an LCD module, potentiometer, LEDs, and plenty of bread-boarding space to meet all of your evaluation needs. The kit includes:

- Evaluation Board with LCD Module
- MiniProg Programming Unit
- 28-Pin CY8C29466-24PXI PDIP PSoC Device Sample (2)
- PSoC Designer Software CD
- Getting Started Guide
- USB 2.0 Cable

CY3214-PSoCEvalUSB

The CY3214-PSoCEvalUSB evaluation kit features a development board for the CY8C24794-24LFXI PSoC device. Special features of the board include both USB and capacitive sensing development and debugging support. This evaluation board also includes an LCD module, potentiometer, LEDs, an enunciator and plenty of bread boarding space to meet all of your evaluation needs. The kit includes:

- PSoCEvalUSB Board
- LCD Module
- MIniProg Programming Unit
- Mini USB Cable
- PSoC Designer and Example Projects CD
- Getting Started Guide
- Wire Pack

Glossary

block	1. A functional unit that performs a single function, such as an oscillator. 2. A functional unit that may be configured to perform one of several functions, such as a digital PSoC block or an analog PSoC block.
buffer	1. A storage area for data that is used to compensate for a speed difference, when transferring data from one device to another. Usually refers to an area reserved for IO operations, into which data is read, or from which data is written. 2. A portion of memory set aside to store data, often before it is sent to an external device or as it is received from an external device. 3. An amplifier used to lower the output impedance of a system.
bus	1. A named connection of nets. Bundling nets together in a bus makes it easier to route nets with similar routing patterns. 2. A set of signals performing a common function and carrying similar data. Typically represented using vector notation; for example, address[7:0]. 3. One or more conductors that serve as a common connection for a group of related devices.
clock	The device that generates a periodic signal with a fixed frequency and duty cycle. A clock is sometimes used to synchronize different logic blocks.
comparator	An electronic circuit that produces an output voltage or current whenever two input levels simultaneously satisfy predetermined amplitude requirements.
compiler	A program that translates a high level language, such as C, into machine language.
configuration space	In PSoC devices, the register space accessed when the XIO bit, in the CPU_F register, is set to ‘1’.
crystal oscillator	An oscillator in which the frequency is controlled by a piezoelectric crystal. Typically a piezoelectric crystal is less sensitive to ambient temperature than other circuit components.
cyclic redundancy check (CRC)	A calculation used to detect errors in data communications, typically performed using a linear feedback shift register. Similar calculations may be used for a variety of other purposes such as data compression.
data bus	A bi-directional set of signals used by a computer to convey information from a memory location to the central processing unit and vice versa. More generally, a set of signals used to convey data between digital functions.
debugger	A hardware and software system that allows you to analyze the operation of the system under development. A debugger usually allows the developer to step through the firmware one step at a time, set break points, and analyze memory.
dead band	A period of time when neither of two or more signals are in their active state or in transition.
digital blocks	The 8-bit logic blocks that can act as a counter, timer, serial receiver, serial transmitter, CRC generator, pseudo-random number generator, or SPI.
digital-to-analog (DAC)	A device that changes a digital signal to an analog signal of corresponding magnitude. The analog-to-digital (ADC) converter performs the reverse operation.
duty cycle	The relationship of a clock period high time to its low time, expressed as a percent.
emulator	Duplicates (provides an emulation of) the functions of one system with a different system, so that the second system appears to behave like the first system.

Glossary

External Reset (XRES)	An active high signal that is driven into the PSoC device. It causes all operation of the CPU and blocks to stop and return to a pre-defined state.
Flash	An electrically programmable and erasable, non-volatile technology that provides you the programmability and data storage of EPROMs, plus in-system erasability. Non-volatile means that the data is retained when power is OFF.
Flash block	The smallest amount of Flash ROM space that may be programmed at one time and the smallest amount of Flash space that may be protected. A Flash block holds 64 bytes.
frequency	The number of cycles or events per unit of time, for a periodic function.
gain	The ratio of output current, voltage, or power to input current, voltage, or power, respectively. Gain is usually expressed in dB.
I^2C	A two-wire serial computer bus by Philips Semiconductors (now NXP Semiconductors). I2C is an Inter-Integrated Circuit. It is used to connect low-speed peripherals in an embedded system. The original system was created in the early 1980s as a battery control interface, but it was later used as a simple internal bus system for building control electronics. I2C uses only two bi-directional pins, clock and data, both running at +5V and pulled high with resistors. The bus operates at 100 kbits/second in standard mode and 400 kbits/second in fast mode.
ICE	The in-circuit emulator that allows you to test the project in a hardware environment, while viewing the debugging device activity in a software environment (PSoC Designer).
input/output (I/O)	A device that introduces data into or extracts data from a system.
interrupt	A suspension of a process, such as the execution of a computer program, caused by an event external to that process, and performed in such a way that the process can be resumed.
interrupt service routine (ISR)	A block of code that normal code execution is diverted to when the M8C receives a hardware interrupt. Many interrupt sources may each exist with its own priority and individual ISR code block. Each ISR code block ends with the RETI instruction, returning the device to the point in the program where it left normal program execution.
jitter	1. A misplacement of the timing of a transition from its ideal position. A typical form of corruption that occurs on serial data streams. 2. The abrupt and unwanted variations of one or more signal characteristics, such as the interval between successive pulses, the amplitude of successive cycles, or the frequency or phase of successive cycles.
low-voltage detect (LVD)	A circuit that senses V_{DD} and provides an interrupt to the system when V_{DD} falls lower than a selected threshold.
M8C	An 8-bit Harvard-architecture microprocessor. The microprocessor coordinates all activity inside a PSoC by interfacing to the Flash, SRAM, and register space.
master device	A device that controls the timing for data exchanges between two devices. Or when devices are cascaded in width, the master device is the one that controls the timing for data exchanges between the cascaded devices and an external interface. The controlled device is called the ***slave device.***
microcontroller	An integrated circuit chip that is designed primarily for control systems and products. In addition to a CPU, a microcontroller typically includes memory, timing circuits, and IO circuitry. The reason for this is to permit the realization of a controller with a minimal quantity of chips, thus achieving maximal possible miniaturization. This in turn, reduces the volume and the cost of the controller. The microcontroller is normally not used for general-purpose computation as is a microprocessor.
mixed-signal	The reference to a circuit containing both analog and digital techniques and components.

Glossary

modulator	A device that imposes a signal on a carrier.
noise	1. A disturbance that affects a signal and that may distort the information carried by the signal. 2. The random variations of one or more characteristics of any entity such as voltage, current, or data.
oscillator	A circuit that may be crystal controlled and is used to generate a clock frequency.
parity	A technique for testing transmitting data. Typically, a binary digit is added to the data to make the sum of all the digits of the binary data either always even (even parity) or always odd (odd parity).
Phase-locked loop (PLL)	An electronic circuit that controls an ***oscillator*** so that it maintains a constant phase angle relative to a reference signal.
pinouts	The pin number assignment: the relation between the logical inputs and outputs of the PSoC device and their physical counterparts in the printed circuit board (PCB) package. Pinouts involve pin numbers as a link between schematic and PCB design (both being computer generated files) and may also involve pin names.
port	A group of pins, usually eight.
Power on reset (POR)	A circuit that forces the PSoC device to reset when the voltage is lower than a pre-set level. This is a type of hardware reset.
PSoC®	Cypress Semiconductor's PSoC® is a registered trademark and Programmable System-on-Chip™ is a trademark of Cypress.
PSoC Designer™	The software for Cypress' Programmable System-on-Chip technology.
pulse width modulator (PWM)	An output in the form of duty cycle which varies as a function of the applied measurand
RAM	An acronym for random access memory. A data-storage device from which data can be read out and new data can be written in.
register	A storage device with a specific capacity, such as a bit or byte.
reset	A means of bringing a system back to a know state. See hardware reset and software reset.
ROM	An acronym for read only memory. A data-storage device from which data can be read out, but new data cannot be written in.
serial	1. Pertaining to a process in which all events occur one after the other. 2. Pertaining to the sequential or consecutive occurrence of two or more related activities in a single device or channel.
settling time	The time it takes for an output signal or value to stabilize after the input has changed from one value to another.
shift register	A memory storage device that sequentially shifts a word either left or right to output a stream of serial data.
slave device	A device that allows another device to control the timing for data exchanges between two devices. Or when devices are cascaded in width, the slave device is the one that allows another device to control the timing of data exchanges between the cascaded devices and an external interface. The controlling device is called the master device.

Document History Page

Document Title: CY8C20134/CY8C20234/CY8C20334/CY8C20434/CY8C20534/CY8C20634, PSoC® Programmable System-on-Chip™ Document Number: 001-05356				
Revision	**ECN**	**Orig. of Change**	**Submission Date**	**Description of Change**
**	404571	HMT	See ECN	New silicon and document (Revision **).
*A	418513	HMT	See ECN	Updated Electrical Specifications, including Storage Temperature and Maximum Input Clock Frequency. Updated Features and Analog System Overview. Modified 32-pin QFN E-PAD dimensions. Added new 32-pin QFN. Add High Output Drive indicator to all P1[x] pinouts. Updated trademarks.
*B	490071	HMT	See ECN	Made datasheet “Final”. Added new Development Tool section. Added OCD pinout and package diagram. Added 16-pin QFN. Updated 24-pin and 32-pin QFN package diagrams to 0.60 max thickness. Changed from commercial to industrial temperature range. Updated Storage Temperature specification and notes. Updated thermal resistance data. Added development tool kit part numbers. Finetuned features and electrical specifications.
*C	788177	HMT	See ECN	Added CapSense SNR requirement reference. Added Low Power Comparator (LPC) AC/DC electrical specifications tables. Added 2.7V minimum specifications. Updated figure standards. Updated Technical Training paragraph. Added QFN package clarifications and dimensions. Updated ECN-ed Amkor dimensioned QFN package diagram revisions.
*D	1356805	HMT / SFVTMP3 / HCL / SFV	See ECN	Updated 24-pin QFN Theta JA. Added External Reset Pulse Width, TXRST, specification. Fixed 48-pin QFN.vsd. Updated the table introduction and high output voltage description in section two. The sentence: "Exceeding maximum ratings may shorten the battery life of the device.” does not apply to all datasheets. Therefore, the word "battery" is changed to "useful.” Took out tabs after table and figure numbers in titles and added two hard spaces. Updated the section, DC GPIO Specifications on page 20 with new text. Updated VOH5 and VOH6 to say, ”High Output Voltage, Port 1 Pins with 3.0V LDO Regulator Enabled.” Updated VOH7 and VOH8 with the text, “maximum of 20 mA source current in all I/Os.”Added 28-pin SSOP part, pinout, package. Updated specs. Modified dev. tool part numbers.
*E	2197347	UVS / AESA	See ECN	Added 32-pin Sawn QFN Pin diagram Removed package diagram: 32-Pin (5 × 5 mm) SAWN QFN(001-42168 *A) Updated Ordering Information table with CY8C20434-12LQXI and CY8C20434-12LQXIT ordering details. Corrected Table 16. DC Programming Specifications - Included above the table "Flash Endurance and Retention specifications with the use of the EEPROM User Module are valid only within the range: 25 °C +/-20C during the Flash Write operation. Refer the EEPROM User Module datasheet instructions for EEPROM Flash Write requirements outside of the 25 °C +/-20 °C temperature window."
*F	2542938	RLRM / AESA	07/30/2008	Corrected Ordering Information format. Updated package diagrams 001-13937 and 001-30999. Updated datasheet template. Corrected Figure 6 (28-pin diagram).
*G	2610469	SNV / PYRS	11/20/08	Updated V_{OH5}, V_{OH7}, and V_{OH9} specifications
*H	2693024	DPT / PYRS	04/16/2009	Changed title from PSoC® Mixed Signal Array to PSoC® Programmable System-on-Chip™ Replaced package outline drawing for 32-Pin Sawn QFN Updated “Development Tool Selection” on page 38 Updated “Development Tools” on page 7 and “Designing with PSoC Designer” on page 8 Updated “Getting Started” on page 6

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Document Title: CY8C20134/CY8C20234/CY8C20334/CY8C20434/CY8C20534/CY8C20634, PSoC® Programmable System-on-Chip™ Document Number: 001-05356				
Revision	**ECN**	**Orig. of Change**	**Submission Date**	**Description of Change**
*I	2717566	DRSW / AESA	06/11/2009	Updated AC Chip-Level, and AC Programming Specifications as follows: Modified F_{IMO6} (page 20), T_{WRITE} specifications (page 23) Added I_{OH}, I_{OL} (page 17), Flash endurance note (page 19), DCILO (page 20), F32K_U (page 20), $T_{POWERUP}$ (page 20), $T_{ERASEALL}$ (page 23), $T_{PROGRAM\_HOT}$ (page 24), and $T_{PROGRAM\_COLD}$ (page 24) specifications Added AC SPI Master and Slave Specifications Added 30-Ball WLCSP Package
*J	2825336	ISW	12/10/2009	Updated pin description table for 48-pin OCD. Updated Ordering information table to include CY8C20534-12PVXA parts. Updated package diagrams for 48-pin QFN, 16-pin QFN (sawn), 24-pin QFN (sawn), and 30-ball WLCSP specs.
*K	2892629	NJF	03/15/2010	Updated Programmable pin configuration details in Features. Updated Analog Multiplexer System. Updated Cypress website links. Updated PSoC Designer Software Subsystems. Added $T_{BAKETEMP}$ and $T_{BAKETIME}$ parameters in Absolute Maximum Ratings. Removed the following sections: DC Low Power Comparator Specifications, AC Analog Mux Bus Specifications, AC Low Power Comparator Specifications, Third Party Tools, and Build a PSoC Emulator into your Board. Modified Notes in Packaging Dimensions. Updated Ordering Code Definitions. Removed inactive parts from Ordering Information. Updated links in Sales, Solutions, and Legal Information.
*L	2872902	VMAD	04/06/2010	Added part number CY8C20134 to the title. Added 8-pin and 16-pin SOIC pin and package details. Updated content to match current style guide and datasheet template. Moved acronyms and units of measure tables to page 35.
*M	3043170	NJF	09/30/2010	Added PSoC Device Characteristics table . Added DC I^2C Specifications table. Added F_{32K_U} max limit. Added Tjit_IMO specification, removed existing jitter specifications. Updated Units of Measure, Acronyms, Glossary, and References sections. Updated solder reflow specifications. No specific changed were made to I^2C Timing Diagram. Updated for clearer understanding. Template and styles update.
*N	3173718	NJF	02/16/2011	CY8C20134-12SX1I and CY8C20234-12SX2I typo error fixed in the ordering information table and changed in to CY8C20134-12SXI and CY8C20234-12SXI. Updated document version and date. Updated package diagram to 001-12919 *C.
*O	3248613	TOF	06/10/2011	Under Table 13, the text "Table 13 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, or 2.4 V to 3.0 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters apply to 5 V, 3.3 V, and 2.7 V at 25 °C. These are for design guidance only." changed to "Table 13 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, or Table 14 for 2.4 V to 3.0 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters apply to 5 V, 3.3 V, and 2.7 V at 25 °C. These are for design guidance only". Updated Table 34 on page 37 table. Updated sections, "Getting Started", "Development Tools", and "Designing with PSoC Designer" to remove references to the system level designs. Updated package diagram 51-85066 to *E revision.
*P	3394775	KPOL	10/04/2011	Updated 16-pin SOIC and 16-pin QFN package drawings.

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